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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	C166SV2
Core Size	16-Bit
Speed	20MHz
Connectivity	EBI/EMI, SPI, UART/USART
Peripherals	PWM, WDT
Number of I/O	79
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	12K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 2.7V
Data Converters	A/D 14x8/10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	100-LQFP
Supplier Device Package	PG-TQFP-100-5
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/saf-xc164s-32f20f-bb

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2.2 Pin Configuration and Definition

The pins of the XC164S are described in detail in **Table 3**, including all their alternate functions. **Figure 2** summarizes all pins in a condensed way, showing their location on the package. E*) mark pins to be used as alternate external interrupt inputs.

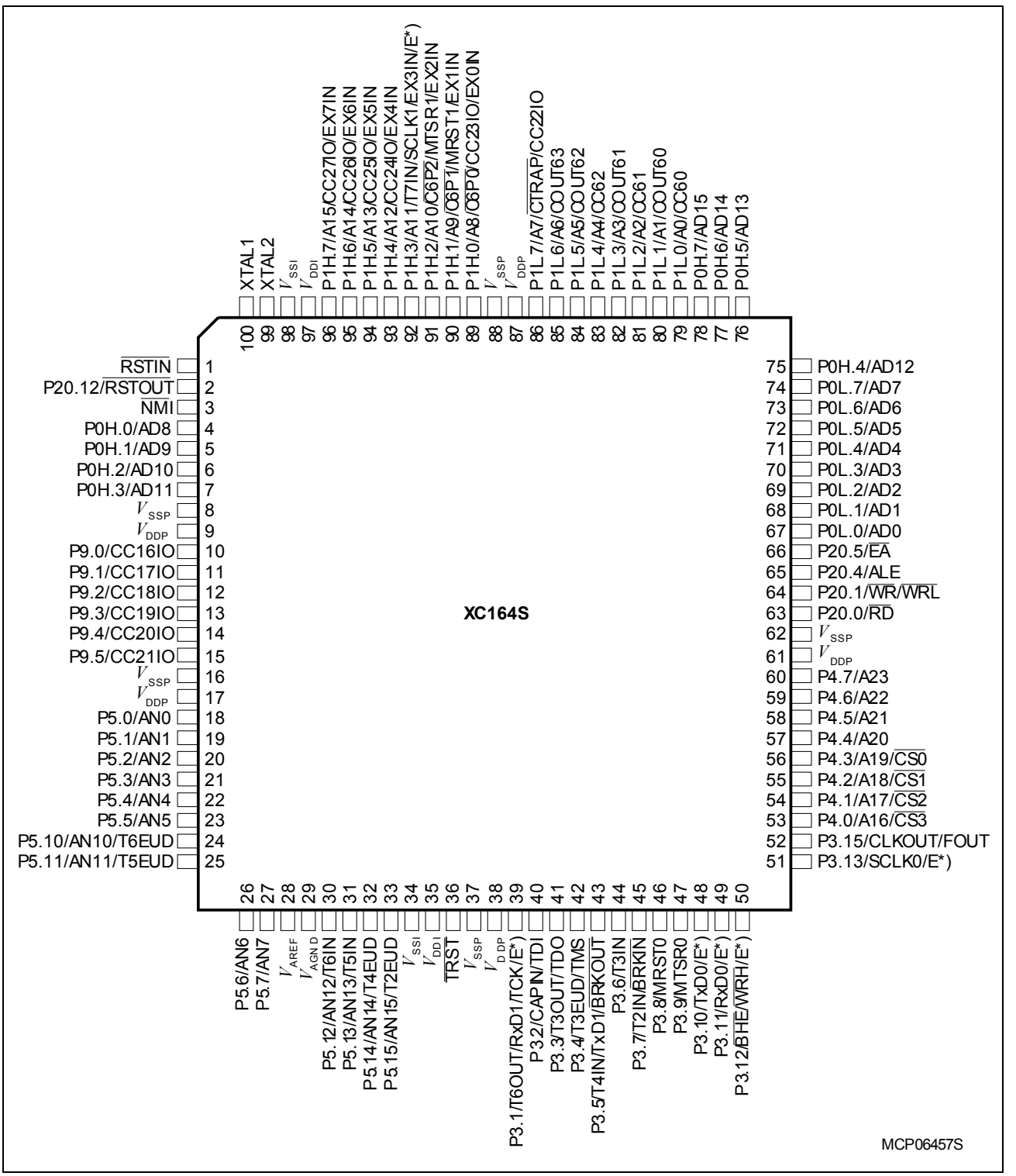


Figure 2 Pin Configuration (top view)

Table 2 Pin Definitions and Functions (cont'd)

Symbol	Pin Num.	Input Outp.	Function
P5		I	Port 5 is a 14-bit input-only port. The pins of Port 5 also serve as analog input channels for the A/D converter, or they serve as timer inputs:
P5.0	18	I	AN0
P5.1	19	I	AN1
P5.2	20	I	AN2
P5.3	21	I	AN3
P5.4	22	I	AN4
P5.5	23	I	AN5
P5.10	24	I	AN10, T6EUD GPT2 Timer T6 Ext. Up/Down Ctrl. Inp.
P5.11	25	I	AN11, T5EUD GPT2 Timer T5 Ext. Up/Down Ctrl. Inp.
P5.6	26	I	AN6
P5.7	27	I	AN7
P5.12	30	I	AN12, T6IN GPT2 Timer T6 Count/Gate Input
P5.13	31	I	AN13, T5IN GPT2 Timer T5 Count/Gate Input
P5.14	32	I	AN14, T4EUD GPT1 Timer T4 Ext. Up/Down Ctrl. Inp.
P5.15	33	I	AN15, T2EUD GPT1 Timer T2 Ext. Up/Down Ctrl. Inp.
$\overline{\text{TRST}}$	36	I	Test-System Reset Input. For normal system operation, pin $\overline{\text{TRST}}$ should be held low. A high level at this pin at the rising edge of $\overline{\text{RSTIN}}$ activates the XC164CM's debug system. In this case, pin $\overline{\text{TRST}}$ must be driven low once to reset the debug system.

3.1 Memory Subsystem and Organization

The memory space of the XC164S is configured in a Von Neumann architecture, which means that all internal and external resources, such as code memory, data memory, registers and I/O ports, are organized within the same linear address space. This common memory space includes 16 Mbytes and is arranged as 256 segments of 64 Kbytes each, where each segment consists of four data pages of 16 Kbytes each. The entire memory space can be accessed bytewise or wordwise. Portions of the on-chip DPRAM and the register spaces (E/SFR) have additionally been made directly bitaddressable.

The internal data memory areas and the Special Function Register areas (SFR and ESFR) are mapped into segment 0, the system segment.

The Program Management Unit (PMU) handles all code fetches and, therefore, controls accesses to the program memories, such as Flash memory, and PSRAM.

The Data Management Unit (DMU) handles all data transfers and, therefore, controls accesses to the DSRAM and the on-chip peripherals.

Both units (PMU and DMU) are connected via the high-speed system bus to exchange data. This is required if operands are read from program memory, code or data is written to the PSRAM, code is fetched from external memory, or data is read from or written to external resources, including peripherals on the LXBus. The system bus allows concurrent two-way communication for maximum transfer performance.

256 Kbytes[1] **of on-chip Flash memory or mask-programmable ROM** store code or constant data. The on-chip Flash memory is organized as four 8-Kbyte sectors, one 32-Kbyte sector, and three 64-Kbyte sector. Each sector can be separately write protected[2], erased and programmed (in blocks of 128 Bytes). The complete Flash or ROM area can be read-protected. A password sequence temporarily unlocks protected areas. The Flash module combines very fast 64-bit one-cycle read accesses with protected and efficient writing algorithms for programming and erasing. Thus, program execution out of the internal Flash results in maximum performance. Dynamic error correction provides extremely high read data security for all read accesses.
For timing characteristics, please refer to **Section 4.4.2**.

6 Kbytes of on-chip Program SRAM (PSRAM) are provided to store user code or data. The PSRAM is accessed via the PMU and is therefore optimized for code fetches.

4 Kbytes[1] **of on-chip Data SRAM (DSRAM)** are provided as a storage for general user data. The DSRAM is accessed via the DMU and is therefore optimized for data accesses.

2 Kbytes of on-chip Dual-Port RAM (DPRAM) are provided as a storage for user defined variables, for the system stack, and general purpose register banks. A register

1) Depends on the respective derivative. The derivatives are listed in **Table 1**.

2) Each two 8-Kbyte sectors are combined for write-protection purposes.

3.2 External Bus Controller

All of the external memory accesses are performed by a particular on-chip External Bus Controller (EBC). It can be programmed either to Single Chip Mode when no external memory is required, or to one of four different external memory access modes[1)], which are as follows:

- 16 … 24-bit Addresses, 16-bit Data, Demultiplexed
- 16 … 24-bit Addresses, 16-bit Data, Multiplexed
- 16 … 24-bit Addresses, 8-bit Data, Multiplexed
- 16 … 24-bit Addresses, 8-bit Data, Demultiplexed

In the demultiplexed bus modes, addresses are output on PORT1 and data is input/output on PORT0 or P0L, respectively. In the multiplexed bus modes both addresses and data use PORT0 for input/output. The high order address (segment) lines use Port 4. The number of active segment address lines is selectable, restricting the external address space to 8 Mbytes … 64 Kbytes. This is required when interface lines are assigned to Port 4.

Up to 4 external $\overline{CS}$ signals (3 windows plus default) can be generated in order to save external glue logic. External modules can directly be connected to the common address/data bus and their individual select lines.

Important timing characteristics of the external bus interface have been made programmable (via registers TCONCSx/FCONCSx) to allow the user the adaption of a wide range of different types of memories and external peripherals.

In addition, up to 4 independent address windows may be defined (via registers ADDRSELx) which control the access to different resources with different bus characteristics. These address windows are arranged hierarchically where window 4 overrides window 3, and window 2 overrides window 1. All accesses to locations not covered by these 4 address windows are controlled by TCONCS0/FCONCS0. The currently active window can generate a chip select signal.

Note: The chip select signal of address window 4 is not available on a pin.

The external bus timing is related to the rising edge of the reference clock output CLKOUT. The external bus protocol is compatible with that of the standard C166 Family.

The EBC also controls accesses to resources connected to the on-chip LXBus. The LXBus is an internal representation of the external bus and allows accessing integrated peripherals and modules in the same way as external components.

1) Bus modes are switched dynamically if several address windows with different mode settings are used.

example, shift and rotate instructions are always processed during one machine cycle independent of the number of bits to be shifted. Also multiplication and most MAC instructions execute in one single cycle. All multiple-cycle instructions have been optimized so that they can be executed very fast as well: for example, a division algorithm is performed in 18 to 21 CPU cycles, depending on the data and division type. Four cycles are always visible, the rest runs in the background. Another pipeline optimization, the branch target prediction, allows eliminating the execution time of branch instructions if the prediction was correct.

The CPU has a register context consisting of up to three register banks with 16 wordwide GPRs each at its disposal. The global register bank is physically allocated within the on-chip DPRAM area. A Context Pointer (CP) register determines the base address of the active global register bank to be accessed by the CPU at any time. The number of register banks is only restricted by the available internal RAM space. For easy parameter passing, a register bank may overlap others.

A system stack of up to 32 Kwords is provided as a storage for temporary data. The system stack can be allocated to any location within the address space (preferably in the on-chip RAM area), and it is accessed by the CPU via the stack pointer (SP) register. Two separate SFRs, STKOV and STKUN, are implicitly compared against the stack pointer value upon each stack access for the detection of a stack overflow or underflow.

The high performance offered by the hardware implementation of the CPU can efficiently be utilized by a programmer via the highly efficient XC164S instruction set which includes the following instruction classes:

- Standard Arithmetic Instructions
- DSP-Oriented Arithmetic Instructions
- Logical Instructions
- Boolean Bit Manipulation Instructions
- Compare and Loop Control Instructions
- Shift and Rotate Instructions
- Prioritize Instruction
- Data Movement Instructions
- System Stack Instructions
- Jump and Call Instructions
- Return Instructions
- System Control Instructions
- Miscellaneous Instructions

The basic instruction length is either 2 or 4 bytes. Possible operand types are bits, bytes and words. A variety of direct, indirect or immediate addressing modes are provided to specify the required operands.

3.5 On-Chip Debug Support (OCDS)

The On-Chip Debug Support system provides a broad range of debug and emulation features built into the XC164S. The user software running on the XC164S can thus be debugged within the target system environment.

The OCDS is controlled by an external debugging device via the debug interface, consisting of the IEEE-1149-conforming JTAG port and a break interface. The debugger controls the OCDS via a set of dedicated registers accessible via the JTAG interface. Additionally, the OCDS system can be controlled by the CPU, e.g. by a monitor program. An injection interface allows the execution of OCDS-generated instructions by the CPU.

Multiple breakpoints can be triggered by on-chip hardware, by software, or by an external trigger input. Single stepping is supported as well as the injection of arbitrary instructions and read/write access to the complete internal address space. A breakpoint trigger can be answered with a CPU-halt, a monitor call, a data transfer, or/and the activation of an external signal.

Tracing data can be obtained via the JTAG interface or via the external bus interface for increased performance.

The debug interface uses a set of 6 interface signals (4 JTAG lines, 2 break lines) to communicate with external circuitry. These interface signals are realized as alternate functions on Port 3 pins.

Complete system emulation is supported by the New Emulation Technology (NET) interface.

3.6 Capture/Compare Units (CAPCOM1/2)

The CAPCOM units support generation and control of timing sequences on up to 32 channels with a maximum resolution of 1 system clock cycle (8 cycles in staggered mode). The CAPCOM units are typically used to handle high speed I/O tasks such as pulse and waveform generation, pulse width modulation (PMW), Digital to Analog (D/A) conversion, software timing, or time recording relative to external events.

Four 16-bit timers (T0/T1, T7/T8) with reload registers provide two independent time bases for each capture/compare register array.

The input clock for the timers is programmable to several prescaled values of the internal system clock, or may be derived from an overflow/underflow of timer T6 in module GPT2. This provides a wide range of variation for the timer period and resolution and allows precise adjustments to the application specific requirements. In addition, external count inputs for CAPCOM timers T0 and T7 allow event scheduling for the capture/compare registers relative to external events.

Both of the two capture/compare register arrays contain 16 dual purpose capture/compare registers, each of which may be individually allocated to either CAPCOM timer T0 or T1 (T7 or T8, respectively), and programmed for capture or

compare function.
12 registers of the CAPCOM2 module have each one port pin associated with it which serves as an input pin for triggering the capture function, or as an output pin to indicate the occurrence of a compare event.

Table 6 Compare Modes (CAPCOM1/2)

Compare Modes	Function
Mode 0	Interrupt-only compare mode; several compare interrupts per timer period are possible
Mode 1	Pin toggles on each compare match; several compare events per timer period are possible
Mode 2	Interrupt-only compare mode; only one compare interrupt per timer period is generated
Mode 3	Pin set ‘1’ on match; pin reset ‘0’ on compare timer overflow; only one compare event per timer period is generated
Double Register Mode	Two registers operate on one pin; pin toggles on each compare match; several compare events per timer period are possible
Single Event Mode	Generates single edges or pulses; can be used with any compare mode

When a capture/compare register has been selected for capture mode, the current contents of the allocated timer will be latched (‘captured’) into the capture/compare register in response to an external event at the port pin which is associated with this register. In addition, a specific interrupt request for this capture/compare register is generated. Either a positive, a negative, or both a positive and a negative external signal transition at the pin can be selected as the triggering event.

The contents of all registers which have been selected for one of the five compare modes are continuously compared with the contents of the allocated timers.

When a match occurs between the timer value and the value in a capture/compare register, specific actions will be taken based on the selected compare mode.

3.9 Real Time Clock

The Real Time Clock (RTC) module of the XC164S is directly clocked via a separate clock driver with the prescaled on-chip main oscillator frequency ($f_{RTC} = f_{OSCm}/32$). It is therefore independent from the selected clock generation mode of the XC164S.

The RTC basically consists of a chain of divider blocks:

- a selectable 8:1 divider (on - off)
- the reloadable 16-bit timer T14
- the 32-bit RTC timer block (accessible via registers RTCH and RTCL), made of:
  - a reloadable 10-bit timer
  - a reloadable 6-bit timer
  - a reloadable 6-bit timer
  - a reloadable 10-bit timer

All timers count up. Each timer can generate an interrupt request. All requests are combined to a common node request.

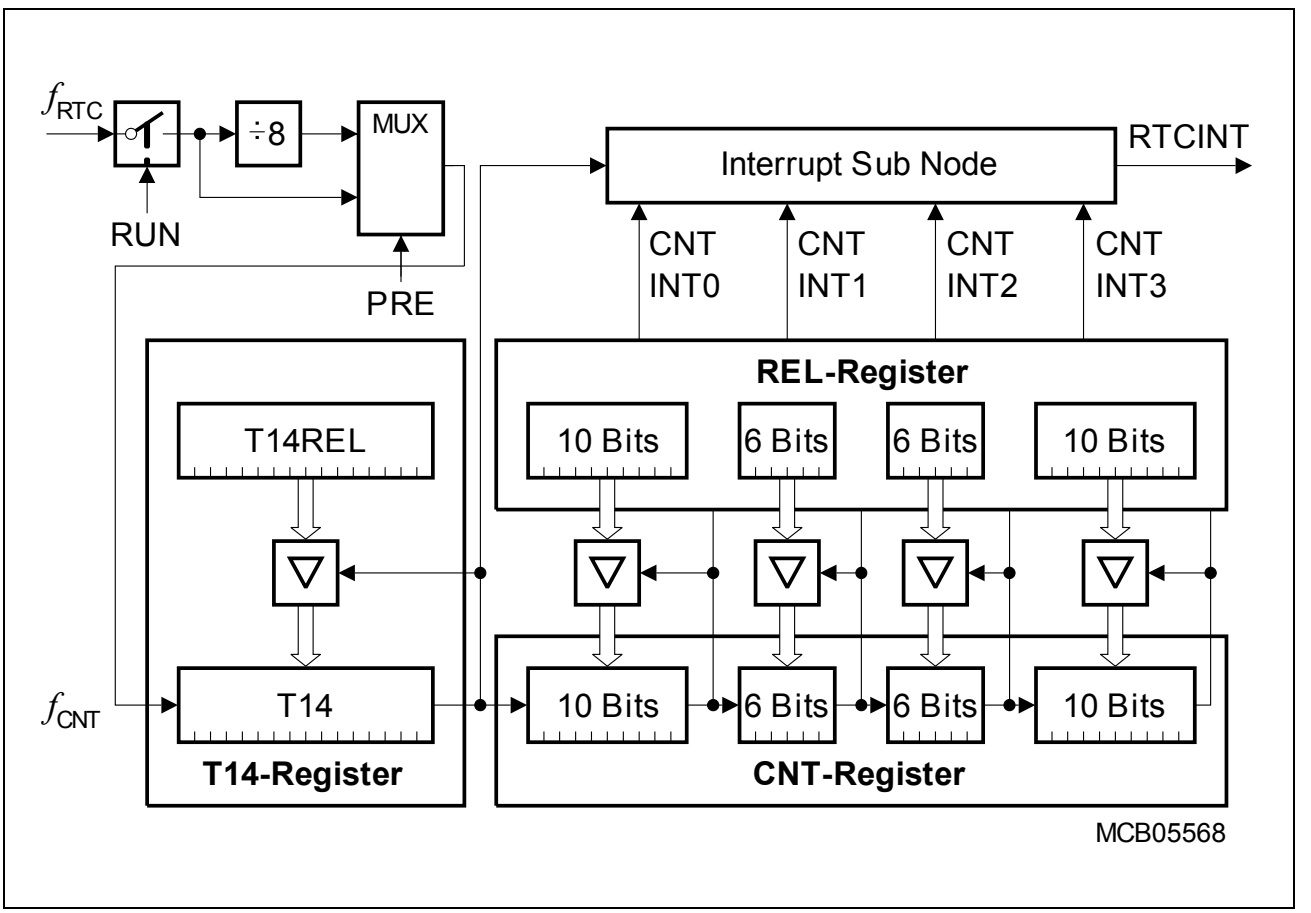


Figure 9 RTC Block Diagram

Note: The registers associated with the RTC are not affected by a reset in order to maintain the correct system time even when intermediate resets are executed.

3.10 A/D Converter

For analog signal measurement, a 10-bit A/D converter with 14 multiplexed input channels and a sample and hold circuit has been integrated on-chip. It uses the method of successive approximation. The sample time (for loading the capacitors) and the conversion time is programmable (in two modes) and can thus be adjusted to the external circuitry. The A/D converter can also operate in 8-bit conversion mode, where the conversion time is further reduced.

Overrun error detection/protection is provided for the conversion result register (ADDAT): either an interrupt request will be generated when the result of a previous conversion has not been read from the result register at the time the next conversion is complete, or the next conversion is suspended in such a case until the previous result has been read.

For applications which require less analog input channels, the remaining channel inputs can be used as digital input port pins.

The A/D converter of the XC164S supports four different conversion modes. In the standard Single Channel conversion mode, the analog level on a specified channel is sampled once and converted to a digital result. In the Single Channel Continuous mode, the analog level on a specified channel is repeatedly sampled and converted without software intervention. In the Auto Scan mode, the analog levels on a prespecified number of channels are sequentially sampled and converted. In the Auto Scan Continuous mode, the prespecified channels are repeatedly sampled and converted. In addition, the conversion of a specific channel can be inserted (injected) into a running sequence without disturbing this sequence. This is called Channel Injection Mode.

The Peripheral Event Controller (PEC) may be used to automatically store the conversion results into a table in memory for later evaluation, without requiring the overhead of entering and exiting interrupt routines for each data transfer.

After each reset and also during normal operation the ADC automatically performs calibration cycles. This automatic self-calibration constantly adjusts the converter to changing operating conditions (e.g. temperature) and compensates process variations.

These calibration cycles are part of the conversion cycle, so they do not affect the normal operation of the A/D converter.

In order to decouple analog inputs from digital noise and to avoid input trigger noise those pins used for analog input can be disconnected from the digital IO or input stages under software control. This can be selected for each pin separately via register P5DIDIS (Port 5 Digital Input Disable).

The Auto-Power-Down feature of the A/D converter minimizes the power consumption when no conversion is in progress.

3.12 High Speed Synchronous Serial Channels (SSC0/SSC1)

The High Speed Synchronous Serial Channels SSC0/SSC1 support full-duplex and half-duplex synchronous communication. It may be configured so it interfaces with serially linked peripheral components, full SPI functionality is supported.

A dedicated baud rate generator allows to set up all standard baud rates without oscillator tuning. For transmission, reception and error handling three separate interrupt vectors are provided.

The SSC transmits or receives characters of 2 … 16 bits length synchronously to a shift clock which can be generated by the SSC (master mode) or by an external master (slave mode). The SSC can start shifting with the LSB or with the MSB and allows the selection of shifting and latching clock edges as well as the clock polarity.

A number of optional hardware error detection capabilities has been included to increase the reliability of data transfers. Transmit error and receive error supervise the correct handling of the data buffer. Phase error and baudrate error detect incorrect serial data.

Summary of Features

- Master or Slave mode operation
- Full-duplex or Half-duplex transfers
- Baudrate generation from 20 Mbit/s to 305.18 bit/s (@ 40 MHz)
- Flexible data format
  - Programmable number of data bits: 2 to 16 bits
  - Programmable shift direction: LSB-first or MSB-first
  - Programmable clock polarity: idle low or idle high
  - Programmable clock/data phase: data shift with leading or trailing clock edge
- Loop back option available for testing purposes
- Interrupt generation on transmitter buffer empty condition, receive buffer full condition, error condition (receive, phase, baudrate, transmit error)
- Three pin interface with flexible SSC pin configuration

Table 7 Summary of the XC164S's Parallel Ports

Port	Control	Alternate Functions
PORT0	Pad drivers	Address/Data lines or data lines[1)]
PORT1	Pad drivers	Address lines[2)]
		Capture inputs or compare outputs, Serial interface lines, Fast external interrupt inputs
Port 3	Pad drivers, Open drain, Input threshold	Timer control signals, serial interface lines, Optional bus control signal $\overline{BHE}$/$\overline{WRH}$, System clock output CLKOUT (or FOUT), Debug interface lines
Port 4	Pad drivers, Open drain, Input threshold	Segment address lines[3)]
		Optional chip select signals
Port 5	–	Analog input channels to the A/D converter, Timer control signals
Port 9	Pad drivers, Open drain, Input threshold	Capture inputs or compare outputs
Port 20	Pad drivers, Open drain	Bus control signals $\overline{RD}$, $\overline{WR}$/$\overline{WRL}$, ALE, External access enable pin $\overline{EA}$, Reset indication output $\overline{RSTOUT}$

1) For multiplexed bus cycles.

2) For demultiplexed bus cycles.

3) For more than 64 Kbytes of external resources.

5) Overload conditions occur if the standard operating conditions are exceeded, i.e. the voltage on any pin exceeds the specified range: $V_{OV} > V_{DDP} + 0.5$ V ($I_{OV} > 0$) or $V_{OV} < V_{SS} - 0.5$ V ($I_{OV} < 0$). The absolute sum of input overload currents on all pins may not exceed **50 mA**. The supply voltages must remain within the specified limits.
   Proper operation is not guaranteed if overload conditions occur on functional pins such as XTAL1, $\overline{RD}$, $\overline{WR}$, etc.
6) Not subject to production test - verified by design/characterization.
7) An overload current (I_{OV}) through a pin injects a certain error current (I_{INJ}) into the adjacent pins. This error current adds to the respective pin's leakage current (I_{OZ}). The amount of error current depends on the overload current and is defined by the overload coupling factor K_{OV}. The polarity of the injected error current is inverse compared to the polarity of the overload current that produces it.
   The total current through a pin is $|I_{TOT}| = |I_{OZ}| + (|I_{OV}| \times K_{OV})$. The additional error current may distort the input voltage on analog inputs.
8) The timing is valid for pin drivers operating in default current mode (selected after reset). Reducing the output current may lead to increased delays or reduced driving capability (C_L).

Parameter Interpretation

The parameters listed in the following partly represent the characteristics of the XC164S and partly its demands on the system. To aid in interpreting the parameters right, when evaluating them for a design, they are marked in column “Symbol”:

CC (**C**ontroller **C**haracteristics):
The logic of the XC164S will provide signals with the respective characteristics.

SR (**S**ystem **R**equirement):
The external system must provide signals with the respective characteristics to the XC164S.

1) An output current above $|I_{OXnom}|$ may be drawn from up to three pins at the same time.
For any group of 16 neighboring port output pins the total output current in each direction (ΣI_{OL} and $\Sigma\text{-}I_{OH}$) must remain below 50 mA.

Table 13 Power Consumption XC164S (Operating Conditions apply)

Parameter	Sym-bol	Limit Values		Unit	Test Condition
		Min.	Max.		
Power supply current (active) with all peripherals active	I_{DDI}	–	10 + 3.0 × f_{CPU}	mA	f_{CPU} in [MHz] 1)2)
Pad supply current	I_{DDP}	–	5	mA	3)
Idle mode supply current with all peripherals active	I_{IDX}	–	10 + 1.3 × f_{CPU}	mA	f_{CPU} in [MHz] 2)
Sleep and Power down mode supply current caused by leakage 4)	I_{PDL} 5)	–	128,000 × $e^{-\alpha}$	mA	V_{DDI} = V_{DDImax} 6) T_J in [°C] α = 4670 / (273 + T_J)
Sleep and Power down mode supply current caused by leakage and the RTC running, clocked by the main oscillator 4)	I_{PDM} 7)	–	0.6 + 0.02 × f_{OSC} + I_{PDL}	mA	V_{DDI} = V_{DDImax} f_{OSC} in [MHz]

1) During Flash programming or erase operations the supply current is increased by max. 5 mA.

2) The supply current is a function of the operating frequency. This dependency is illustrated in **Figure 10**. These parameters are tested at V_{DDImax} and maximum CPU clock frequency with all outputs disconnected and all inputs at V_{IL} or V_{IH}.

3) The pad supply voltage pins (V_{DDP}) mainly provides the current consumed by the pin output drivers. A small amount of current is consumed even though no outputs are driven, because the drivers' input stages are switched and also the Flash module draws some power from the V_{DDP} supply.

4) The total supply current in Sleep and Power down mode is the sum of the temperature dependent leakage current and the frequency dependent current for RTC and main oscillator (if active).

5) This parameter is determined mainly by the transistor leakage currents. This current heavily depends on the junction temperature (see **Figure 12**). The junction temperature T_J is the same as the ambient temperature T_A if no current flows through the port output drivers. Otherwise, the resulting temperature difference must be taken into account.

6) All inputs (including pins configured as inputs) at 0 V to 0.1 V or at V_{DDP} - 0.1 V to V_{DDP}, all outputs (including pins configured as outputs) disconnected. This parameter is tested at 25 °C and is valid for $T_J \geq$ 25 °C.

7) This parameter is determined mainly by the current consumed by the oscillator switched to low gain mode (see **Figure 11**). This current, however, is influenced by the external oscillator circuitry (crystal, capacitors). The given values refer to a typical circuitry and may change in case of a not optimized external oscillator circuitry.

4.3 Analog/Digital Converter Parameters

Table 14 A/D Converter Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit	Test Condition
			Min.	Max.		
Analog reference supply	V_{AREF}	SR	4.5	V_{DDP} + 0.1	V	1)
Analog reference ground	V_{AGND}	SR	V_{SS} - 0.1	V_{SS} + 0.1	V	–
Analog input voltage range	V_{AIN}	SR	V_{AGND}	V_{AREF}	V	2)
Basic clock frequency	f_{BC}		0.5	20	MHz	3)
Conversion time for 10-bit result[4]	t_{C10P}	CC	$52 \times t_{BC} + t_S + 6 \times t_{SYS}$		–	Post-calibr. on
	t_{C10}	CC	$40 \times t_{BC} + t_S + 6 \times t_{SYS}$		–	Post-calibr. off
Conversion time for 8-bit result[4]	t_{C8P}	CC	$44 \times t_{BC} + t_S + 6 \times t_{SYS}$		–	Post-calibr. on
	t_{C8}	CC	$32 \times t_{BC} + t_S + 6 \times t_{SYS}$		–	Post-calibr. off
Calibration time after reset	t_{CAL}	CC	484	11,696	t_{BC}	5)
Total unadjusted error	TUE	CC	–	±2	LSB	1)
Total capacitance of an analog input	C_{AINT}	CC	–	15	pF	6)
Switched capacitance of an analog input	C_{AINS}	CC	–	10	pF	6)
Resistance of the analog input path	R_{AIN}	CC	–	2	kΩ	6)
Total capacitance of the reference input	C_{AREFT}	CC	–	20	pF	6)
Switched capacitance of the reference input	C_{AREFS}	CC	–	15	pF	6)
Resistance of the reference input path	R_{AREF}	CC	–	1	kΩ	6)

1) TUE is tested at $V_{AREF} = V_{DDP} + 0.1$ V, $V_{AGND} = 0$ V. It is verified by design for all other voltages within the defined voltage range.
If the analog reference supply voltage drops below 4.5 V (i.e. $V_{AREF} \geq 4.0$ V) or exceeds the power supply voltage by up to 0.2 V (i.e. $V_{AREF} = V_{DDP} + 0.2$ V) the maximum TUE is increased to ±3 LSB. This range is not subject to production test.
The specified TUE is guaranteed only, if the absolute sum of input overload currents on Port 5 pins (see I_{OV} specification) does not exceed 10 mA, and if V_{AREF} and V_{AGND} remain stable during the respective period of time. During the reset calibration sequence the maximum TUE may be ±4 LSB.

2) V_{AIN} may exceed V_{AGND} or V_{AREF} up to the absolute maximum ratings. However, the conversion result in these cases will be $X000_H$ or $X3FF_H$, respectively.

Table 16 VCO Bands for PLL Operation[1)]

PLLCON.PLLVB	VCO Frequency Range	Base Frequency Range
00	100 … 150 MHz	20 … 80 MHz
01	150 … 200 MHz	40 … 130 MHz
10	200 … 250 MHz	60 … 180 MHz
11	Reserved	

1) Not subject to production test - verified by design/characterization.

4.4.3 External Clock Drive XTAL1

Table 19 External Clock Drive Characteristics (Operating Conditions apply)

Parameter	Symbol		Limit Values		Unit
			Min.	Max.	
Oscillator period	t_{OSC}	SR	25	250[1)]	ns
High time[2)]	t_1	SR	6	–	ns
Low time[2)]	t_2	SR	6	–	ns
Rise time[2)]	t_3	SR	–	8	ns
Fall time[2)]	t_4	SR	–	8	ns

1) The maximum limit is only relevant for PLL operation to ensure the minimum input frequency for the PLL.

2) The clock input signal must reach the defined levels V_{ILC} and V_{IHC}.

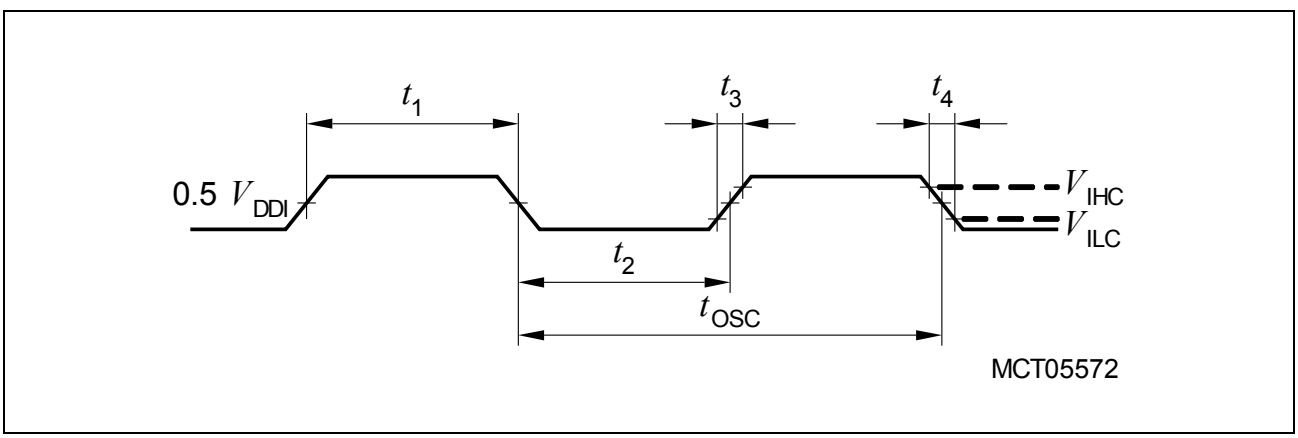
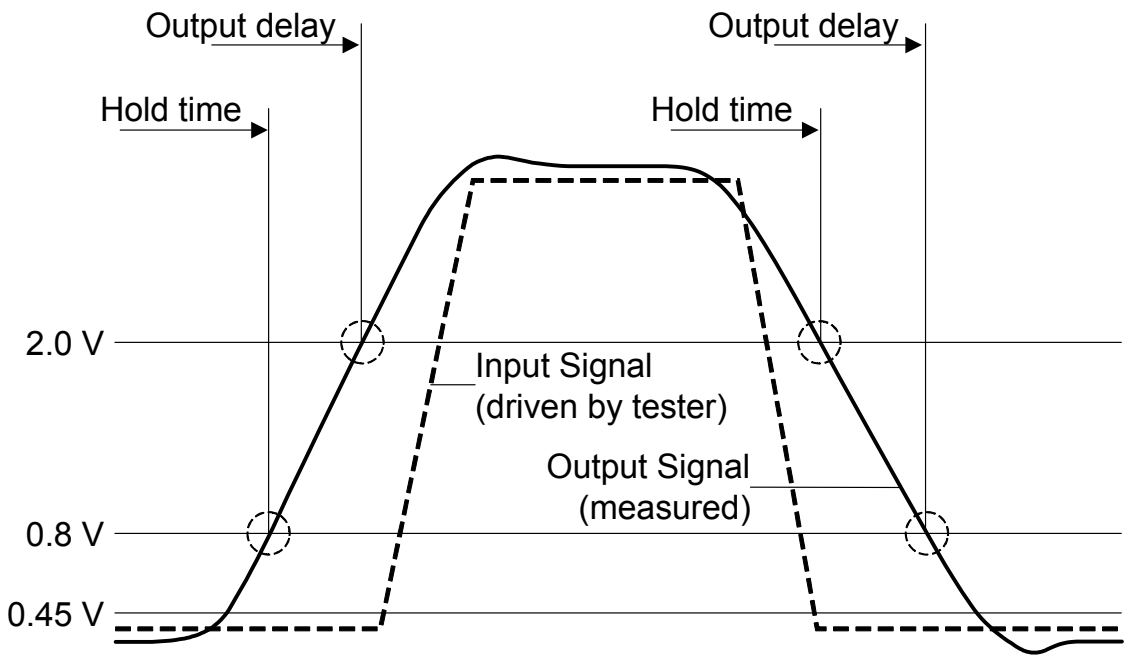


Figure 16 External Clock Drive XTAL1

Note: If the on-chip oscillator is used together with a crystal or a ceramic resonator, the oscillator frequency is limited to a range of 4 MHz to 16 MHz.
It is strongly recommended to measure the oscillation allowance (negative resistance) in the final target system (layout) to determine the optimum parameters for the oscillator operation. Please refer to the limits specified by the crystal supplier.
When driven by an external clock signal it will accept the specified frequency range. Operation at lower input frequencies is possible but is verified by design only (not subject to production test).

4.4.4 Testing Waveforms



Output timings refer to the rising edge of CLKOUT.
Input timings are calculated from the time, when the input signal reaches V_{IH} or V_{IL}, respectively.

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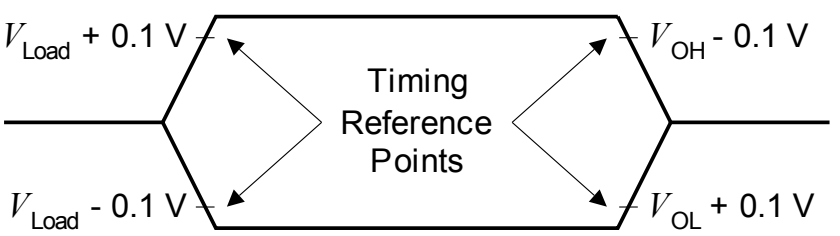
Figure 17 Input Output Waveforms



For timing purposes a port pin is no longer floating when a 100 mV change from load voltage occurs, but begins to float when a 100 mV change from the loaded V_{OH}/V_{OL} level occurs (I_{OH}/I_{OL} = 20 mA).

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Figure 18 Float Waveforms

Variable Memory Cycles

External bus cycles of the XC164S are executed in five subsequent cycle phases (AB, C, D, E, F). The duration of each cycle phase is programmable (via the TCONCSx registers) to adapt the external bus cycles to the respective external module (memory, peripheral, etc.).

This table provides a summary of the phases and the respective choices for their duration.

Table 21 Programmable Bus Cycle Phases (see timing diagrams)

Bus Cycle Phase	Parameter	Valid Values	Unit
Address setup phase, the standard duration of this phase (1 … 2 TCP) can be extended by 0 … 3 TCP if the address window is changed	tp_{AB}	1 … 2 (5)	TCP
Command delay phase	tp_{C}	0 … 3	TCP
Write Data setup/MUX Tristate phase	tp_{D}	0 … 1	TCP
Access phase	tp_{E}	1 … 32	TCP
Address/Write Data hold phase	tp_{F}	0 … 3	TCP

Note: The bandwidth of a parameter (minimum and maximum value) covers the whole operating range (temperature, voltage) as well as process variations. Within a given device, however, this bandwidth is smaller than the specified range. This is also due to interdependencies between certain parameters. Some of these interdependencies are described in additional notes (see standard timing).

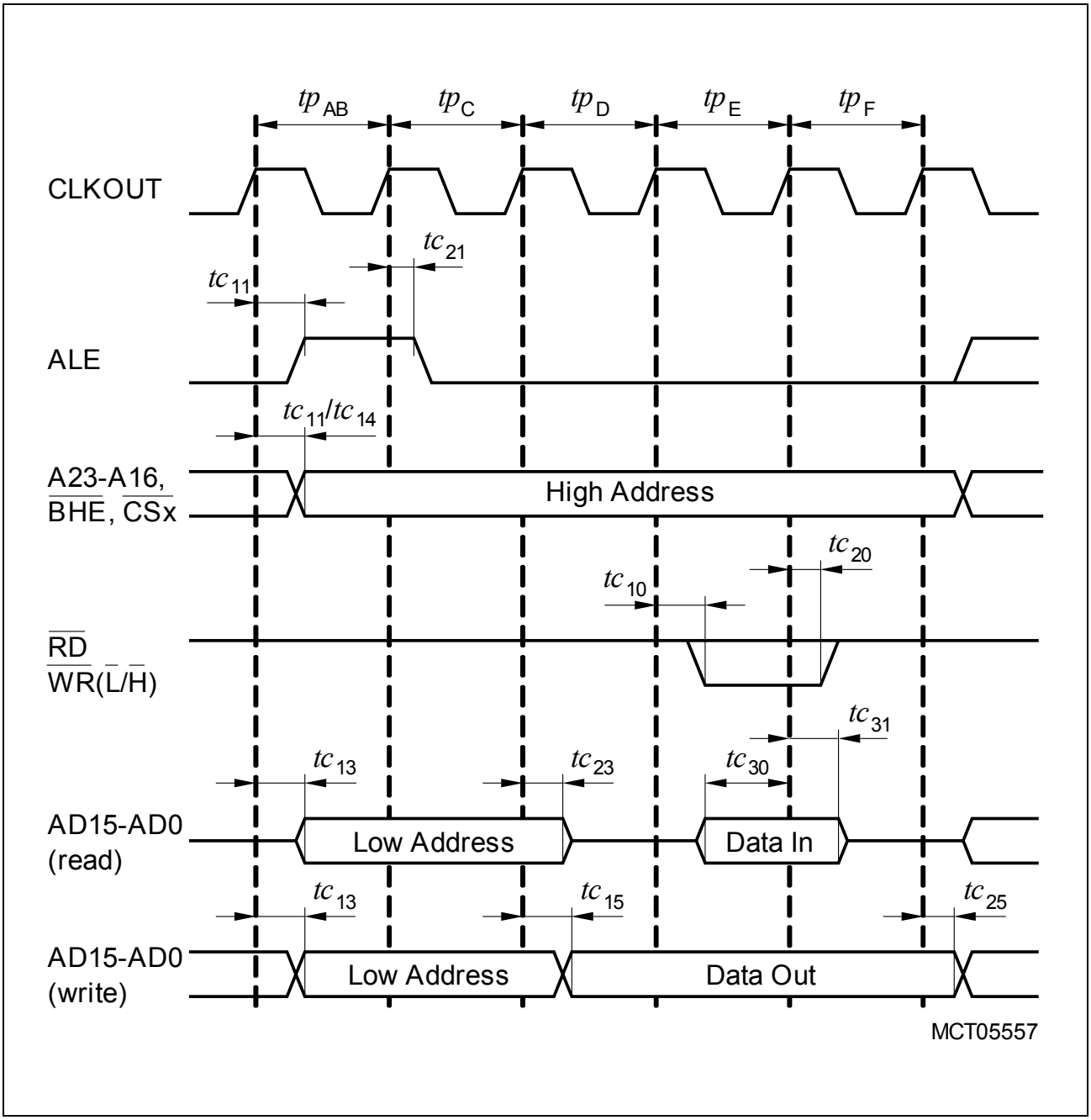

Figure 20 Multiplexed Bus Cycle